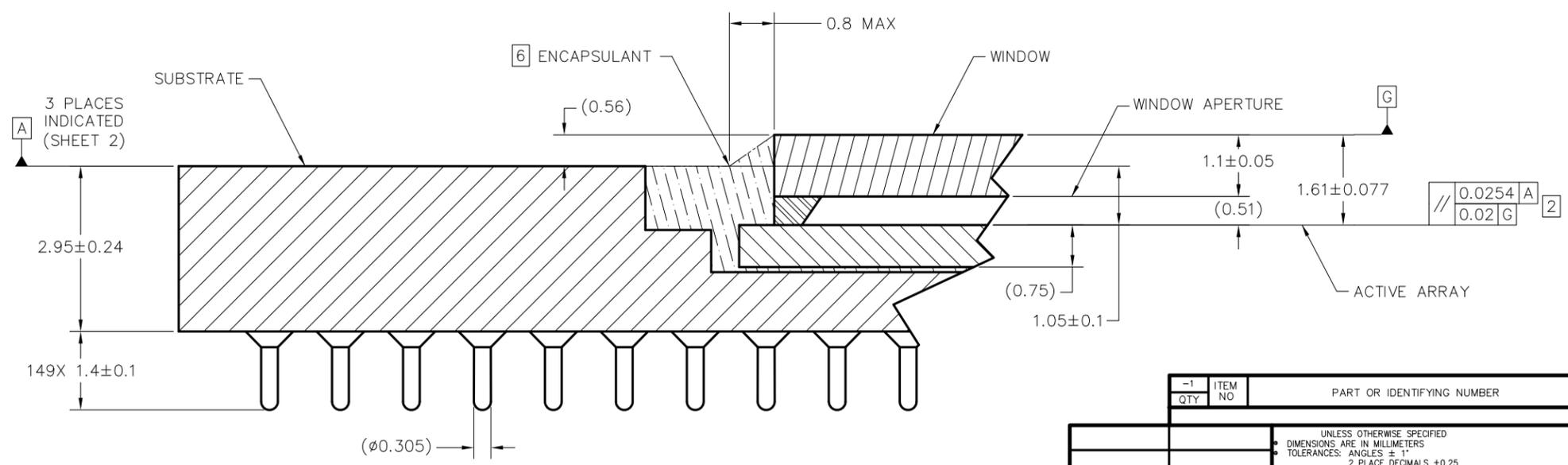
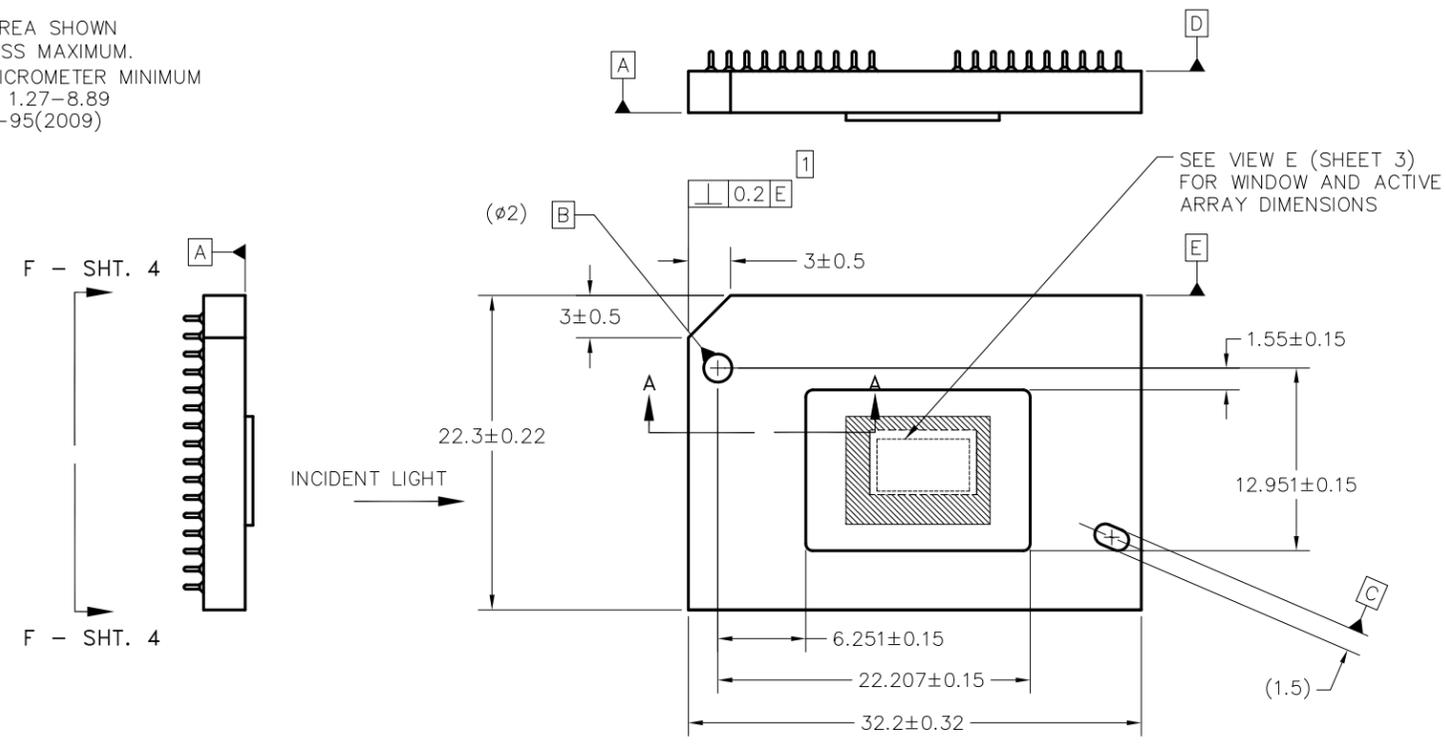


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2142364, INITIAL RELEASE	06/03/2014	M. AVERY
B	ECO 2153319, UPDATE PACKAGE DESIGNATOR IN TITLE BLOCK, NOTE 8 FIXED FOR Ni/Pd/Au, MOVED SUPPLIER CODE IN VIEW F-F.	09/11/2015	M. AVERY
C	ECO 2158233, UPDATE VIEW F-F 3 DIGIT P/N	05/18/2016	M. AVERY
D	ECO 2168572, CHG DIE HEIGHT TOL, WAS ± 0.08	08/25/2017	M. AVERY

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 5 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 6 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.2 THICKNESS MAXIMUM.
- 7 INDICATED CERAMIC SUBSTRATE FEATURES TO BE PLATED WITH 0.3 MICROMETER MINIMUM ELECTROLYTIC GOLD OVER 0.1 MICROMETER MINIMUM PALLADIUM OVER 1.27-8.89 MICROMETERS ELECTROLYTIC NICKEL PER ASTM B488-01, ASTM B679-95(2009) AND AMS-QQ-N-290, RESPECTIVELY.



SECTION A-A  
SCALE 20/1

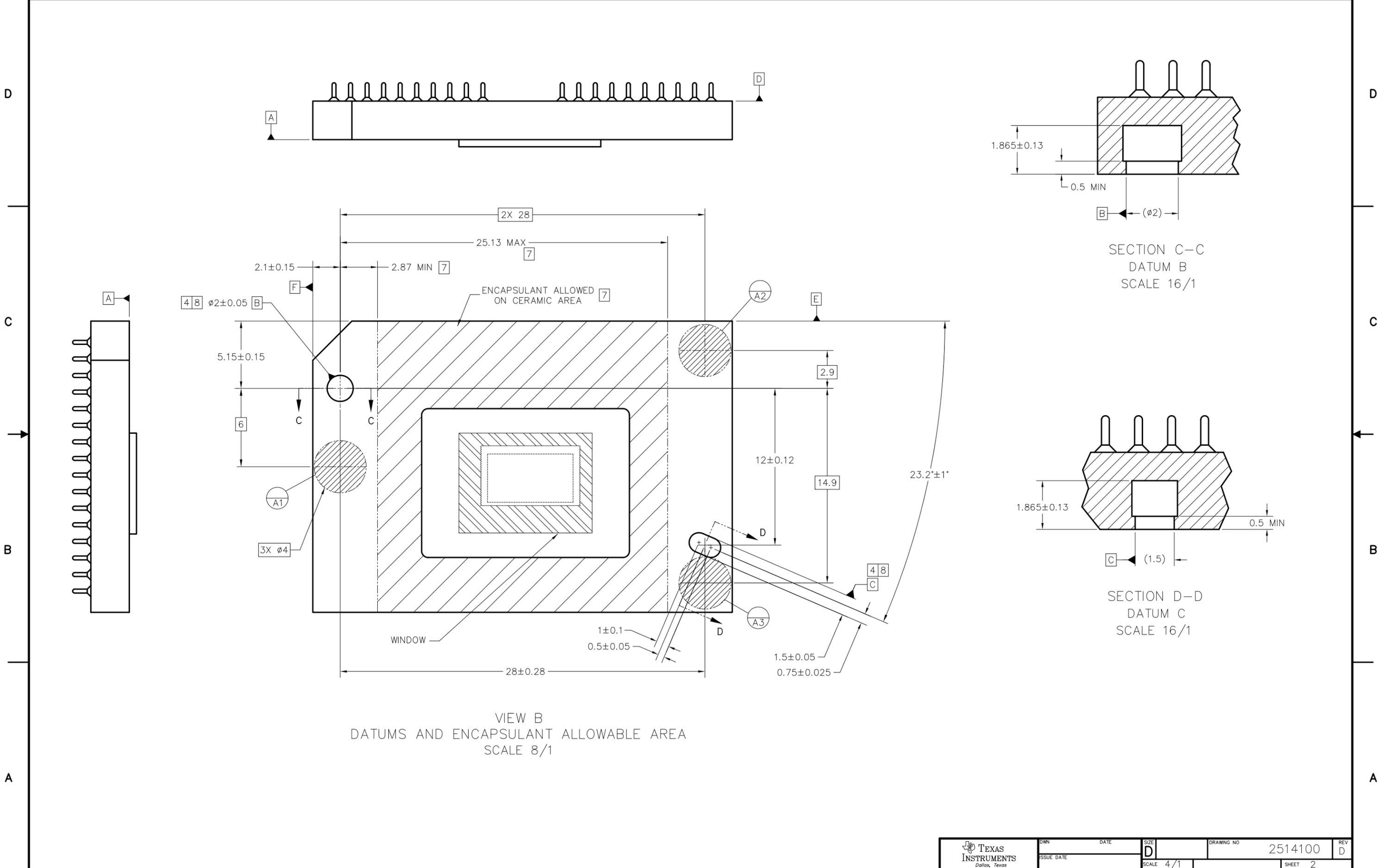
QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
-1				

PARTS LIST		DATE	
DWN	M. AVERY	6/3/14	
ENGR	M. AVERY	6/3/14	
QA	B. HASKETT	6/5/14	
	P. KONRAD	6/13/14	
	R. LONG	6/20/14	
COE	M. DORAK	6/23/14	
	S. SUSI	6/18/14	

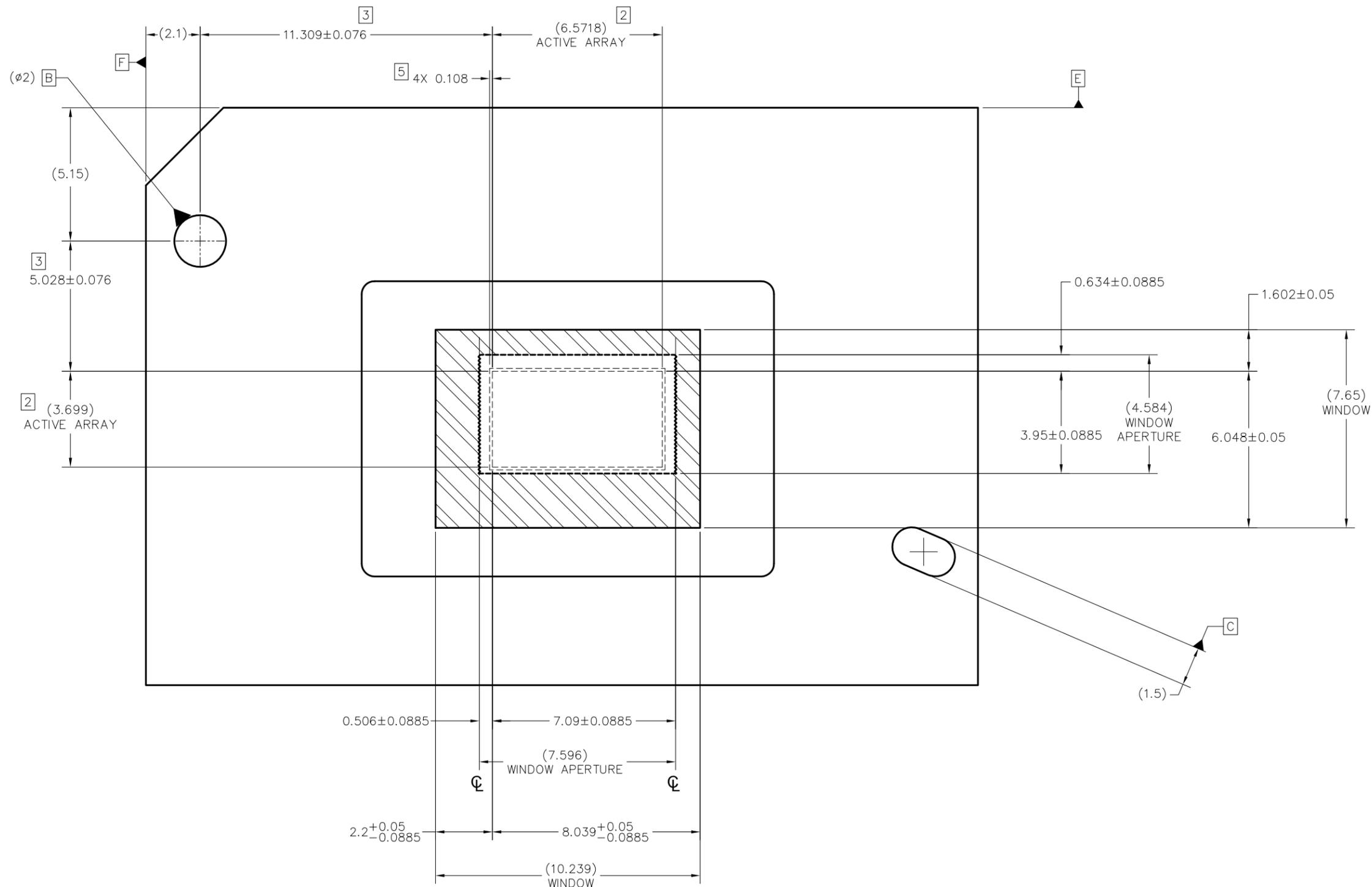
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ± 0.25 3 PLACE DECIMALS ± 0.50	REMOVE ALL BURRS AND SHARP EDGES— INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994 DIMENSIONAL LIMITS APPLY BEFORE PROCESSES— PARENTHEITICAL INFO FOR REF ONLY	TEXAS INSTRUMENTS Dallas, Texas
ICD, MECHANICAL, DMD .3 WVGA DDR SERIES 450 -A1 (FYJ PACKAGE)		
THIRD ANGLE PROJECTION	NONE 0314DA	
	NEXT ASSY USED ON	
	APPLICATION	



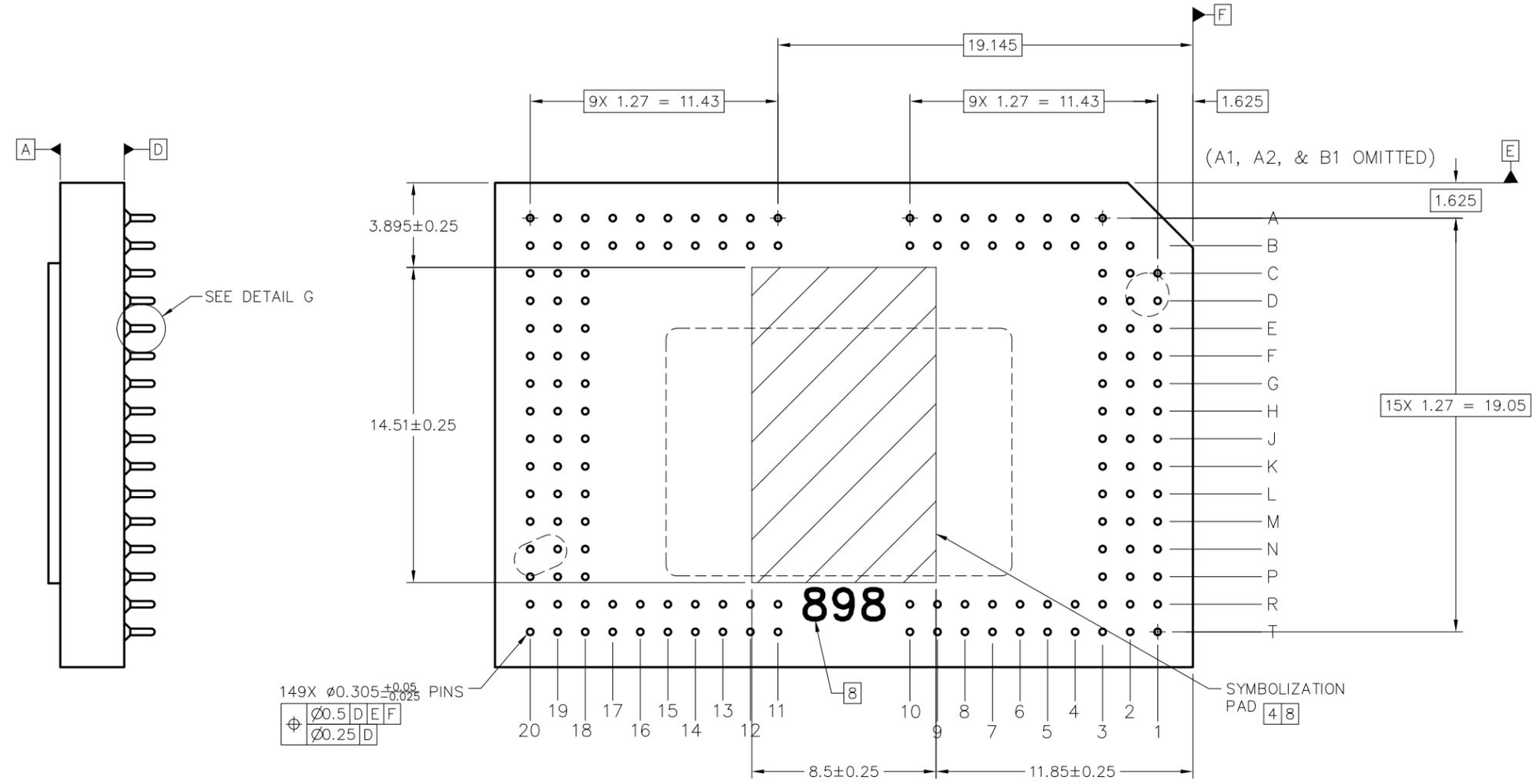
VIEW B  
DATUMS AND ENCAPSULANT ALLOWABLE AREA  
SCALE 8/1

SECTION C-C  
DATUM B  
SCALE 16/1

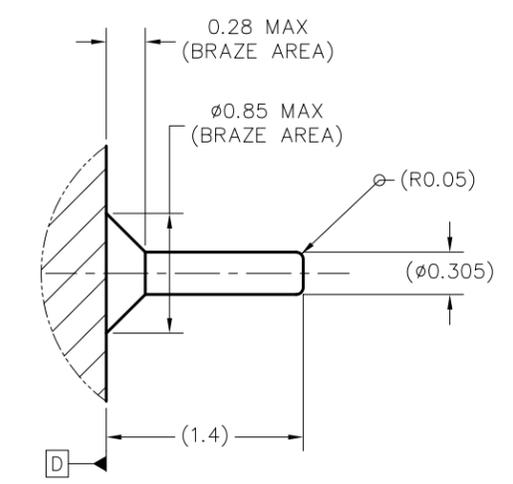
SECTION D-D  
DATUM C  
SCALE 16/1



VIEW E (SHEET 1)  
 DMD WINDOW AND ACTIVE ARRAY  
 SCALE 12:1



VIEW F-F (SHEET 1)  
PINS AND SYMBOLIZATION PAD  
SCALE 8/1



DETAIL G (149 PLACES) [8]  
PIN & BRAZE DIMENSIONS  
SCALE 40/1

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